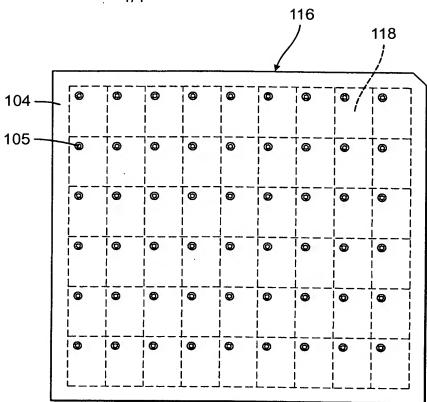
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FIG. 1

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FIG. 2

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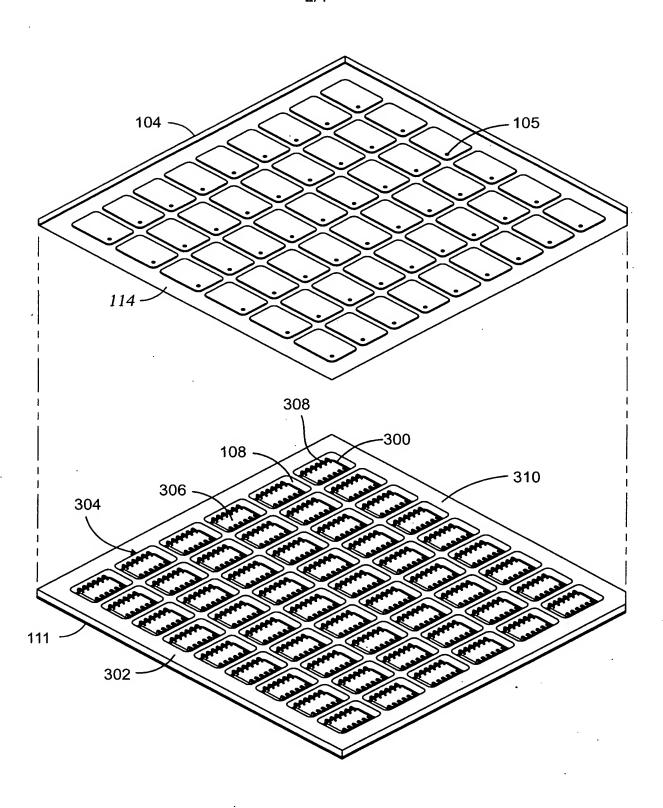


FIG. 3

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4/4 **START** MOLD LID WITH VENT HOLES **~702** MOLD GRID OF SIDEWALLS TO FORM 704 **BASE CAVITY PACKAGES** CURE SIDEWALLS - 706 ATTACH DIE TO SUBSTRATE IN EACH CAVITY **- 708** BOND LEAD WIRES TO BONDING PADS **-710** APPLY ADHESIVE TO CAVITY SIDEWALLS -712 PRESS LID ONTO THE BASE CAVITY SIDEWALLS WITH VENT HOLES ALIGNED **-714** WITH CAVITIES CURE LID ADHESIVE AND BAKE -716 **OUT MOISTURE** SEAL VENT HOLES WITH **-718** ADHESIVE AND CURE MARKING **一720** SAW ASSEMBLY INTO INDIVIDUAL AIR CAVITY **-722** COMPONENT PACKAGES PLACE IN TRAY AND SHIP - 724 **END** FIG. 7

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